



OPA241 OPA2241 OPA4241

OPA251 OPA2251 OPA4251

Single-Supply, *Micro*POWER OPERATIONAL AMPLIFIERS

OPA241 Family optimized for +5V supply. **OPA251 Family** optimized for ±15V supply.

FEATURES

- MicroPOWER: I_Q = 25μA
- SINGLE-SUPPLY OPERATION
- RAIL-TO-RAIL OUTPUT (within 50mV)
- WIDE SUPPLY RANGE Single Supply: +2.7V to +36V Dual Supply: ±1.35V to ±18V
- LOW OFFSET VOLTAGE: ±250μV max
- HIGH COMMON-MODE REJECTION: 124dB
- HIGH OPEN-LOOP GAIN: 128dBSINGLE, DUAL, AND QUAD

APPLICATIONS

- BATTERY OPERATED INSTRUMENTS
- PORTABLE DEVICES
- MEDICAL INSTRUMENTS
- TEST EQUIPMENT

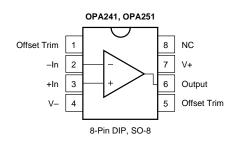
DESCRIPTION

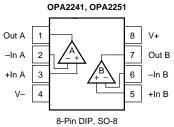
The OPA241 series and OPA251 series are specifically designed for battery powered, portable applications. In addition to very low power consumption (25 μ A), these amplifiers feature low offset voltage, rail-to-rail output swing, high common-mode rejection, and high open-loop gain.

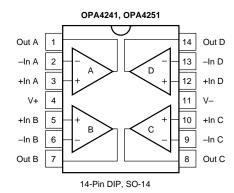
The OPA241 series is optimized for operation at low power supply voltage while the OPA251 series is optimized for high power supplies. Both can operate from either single (+2.7V to +36V) or dual supplies (±1.35V to ±18V). The input common-mode voltage range extends 200mV below the negative supply—ideal for single-supply applications.

They are unity-gain stable and can drive large capacitive loads. Special design considerations assure that these products are easy to use. High performance is maintained as the amplifiers swing to their specified limits. Because the initial offset voltage $(\pm 250\mu V\ max)$ is so low, user adjustment is usually not required. However, external trim pins are provided for special applications (single versions only).

The OPA241 and OPA251 (single versions) are available in standard 8-pin DIP and SO-8 surface-mount packages. The OPA2241 and OPA2251 (dual versions) come in 8-pin DIP and SO-8 surface-mount packages. The OPA4241 and OPA4251 (quad versions) are available in 14-pin DIP and SO-14 surface-mount packages. All are fully specified from -40°C to +85°C and operate from -55°C to +125°C.







International Airport Industrial Park • Mailing Address: PO Box 11400, Tucson, AZ 85734 • Street Address: 6730 S. Tucson Blvd., Tucson, AZ 85766 • Tel: (520) 746-1111 • Twx: 910-952-1111

Internet: http://www.burr-brown.com/ • FAXLine: (800) 548-6133 (US/Canada Only) • Cable: BBRCORP • Telex: 066-6491 • FAX: (520) 889-1510 • Immediate Product Info: (800) 548-6132

SPECIFICATIONS: $V_S = 2.7V$ to 5V

At T_A = +25°C, R_L = 100k Ω connected to $V_S/2$, unless otherwise noted. **Boldface** limits apply over the specified temperature range, $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$.

			OP	A241UA, F A2241UA, A4241UA,	PA	OP	PA PA PA		
PARAMETER		CONDITION	MIN	TYP ⁽¹⁾	MAX	MIN	TYP ⁽¹⁾	MAX	UNITS
OFFSET VOLTAGE Input Offset Voltage $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ vs Temperature vs Power Supply $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ Channel Separation (dual, quad)	V _{OS} dV _{OS} /dT PSRR	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ $V_S = 2.7V \text{ to } 36V$ $V_S = 2.7V \text{ to } 36V$		±50 ±100 ±0.4 3	±250 ± 400 30 30		±100 ±130 ±0.6 *	*	μV μV μV/°C μV/V μV/V
INPUT BIAS CURRENT Input Bias Current ⁽²⁾ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ Input Offset Current $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	I _B			-4 ±0.1	-20 - 25 ±2 ±2		*		nA nA nA nA
NOISE Input Voltage Noise, f = 0.1Hz to 1 Input Voltage Noise Density, f = 1k Current Noise Density, f = 1kHz				1 45 40			* * *		μVp-p nV/√Hz fA/√Hz
INPUT VOLTAGE RANGE Common-Mode Voltage Range Common-Mode Rejection Ratio T _A = -40°C to +85°C	V _{CM} CMRR	$V_{CM} = -0.2V$ to (V+) $-0.8V$ $V_{CM} = 0V$ to (V+) $-0.8V$	-0.2 80 80	106	(V+) -0.8		*		V dB dB
INPUT IMPEDANCE Differential Common-Mode				10 ⁷ 2 10 ⁹ 4			*		Ω pF Ω pF
OPEN-LOOP GAIN Open-Loop Voltage Gain $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	A _{OL}	$\begin{aligned} R_L &= 100k\Omega, \ V_O = (V-)+100mV \ to \ (V+)-100mV \\ R_L &= 100k\Omega, \ V_O = (V-)+100mV \ to \ (V+)-100mV \\ R_L &= 10k\Omega, \ V_O = (V-)+200mV \ to \ (V+)-200mV \\ R_L &= 10k\Omega, \ V_O = (V-)+200mV \ to \ (V+)-200mV \end{aligned}$	100 100 100 100	120 120			*		dB dB dB dB
FREQUENCY RESPONSE Gain-Bandwidth Product Slew Rate Overload Recovery Time	GBW SR	$V_S = 5V, G = 1$ $V_{IN} \cdot G = V_S$		35 0.01 60			* * *		kHz V/μs μs
OUTPUT Voltage Output Swing from Rail ⁽³⁾ $T_A = -40^{\circ}C$ to +85°C	Vo	$R_L = 100k\Omega$ to $V_S/2$, $A_{OL} \ge 70dB$ $R_L = 100k\Omega$ to $V_S/2$, $A_{OL} \ge 100dB$ $R_L = 100k\Omega$ to $V_S/2$, $A_{OL} \ge 100dB$ $R_L = 10k\Omega$ to $V_S/2$, $A_{OL} \ge 100dB$		50 75 100	100 100 200		* *		mV mV mV
T _A = -40°C to +85°C Short-Circuit Current Single Versions Dual, Quad Versions Capacitive Load Drive	I _{SC}	$R_L = 10k\Omega$ to $V_S/2$, $A_{OL} \ge 100dB$	See	-24/+4 -30/+4	200		* *		mV mA mA
POWER SUPPLY Specified Voltage Range Operating Voltage Range Quiescent Current (per amplifier) T _A = -40°C to +85°C	V _s	$T_A = -40^{\circ}C$ to +85°C $I_O = 0$ $I_O = 0$	+2.7	+2.7 to +5 ±25		*	*	*	V V μΑ μΑ
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance	$ heta_{\sf JA}$		-40 -55 -55		+85 +125 +125	* * *		* * *	°C °C °C
8-Pin DIP SO-8 Surface Mount 14-Pin DIP SO-14 Surface Mount	VJA			100 150 80 100			* * *		°C/W °C/W °C/W

^{*} Specifications the same as OPA241UA, PA.

NOTES: (1) $V_S = +5V$. (2) The negative sign indicates input bias current flows out of the input terminals. (3) Output voltage swings are measured between the output and power supply rails.

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SPECIFICATIONS: $V_S = \pm 15V$

At T_A = +25°C, R_L = 100k Ω connected to ground, unless otherwise noted. **Boldface** limits apply over the specified temperature range, T_A = -40°C to +85°C.

			OP	A241UA, I A2241UA, A4241UA,	PA	OPA251UA, PA OPA2251UA, PA OPA4251UA, PA			
PARAMETER		CONDITION	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
OFFSET VOLTAGE Input Offset Voltage $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ vs Temperature vs Power Supply $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ Channel Separation (dual, quad)	V _{OS} dV _{OS} /dT PSRR	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $V_S = \pm 1.35\text{V to } \pm 18\text{V}$ $V_S = \pm 1.35\text{V to } \pm 18\text{V}$		±100 ±150 ±0.6 *	*		±50 ±100 ±0.5 3	±250 ± 300 30 30	μV μV/°C μV/V μV/V μV/V
INPUT BIAS CURRENT Input Bias Current ⁽¹⁾ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ Input Offset Current $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	I _B			*			-4 ±0.1	-20 - 25 ±2 ±2	nA nA nA nA
NOISE Input Voltage Noise, f = 0.1Hz to 1 Input Voltage Noise Density, f = 1k Current Noise Density, f = 1kHz				* * *			1 45 40		μVp-p nV/√Hz fA/√Hz
INPUT VOLTAGE RANGE Common-Mode Voltage Range Common-Mode Rejection Ratio T _A = -40°C to +85°C	V _{CM} CMRR	$V_{CM} = -15.2V$ to 14.2V $V_{CM} = -15V$ to 14.2V		*		(V–) –0.2 100 100	124	(V+) -0.8	V dB dB
INPUT IMPEDANCE Differential Common-Mode				*			10 ⁷ 2 10 ⁹ 4		$\Omega \parallel pF$ $\Omega \parallel pF$
OPEN-LOOP GAIN Open-Loop Voltage Gain $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	A _{OL}	$R_L = 100k\Omega$, $V_O = -14.75V$ to +14.75V $R_L = 100k\Omega$, $V_O = -14.75V$ to +14.75V $R_L = 20k\Omega$, $V_O = -14.7V$ to +14.7V $R_L = 20k\Omega$, $V_O = -14.7V$ to +14.7V		*		100 100 100 100	128 128		dB dB dB dB
FREQUENCY RESPONSE Gain-Bandwidth Product Slew Rate Overload Recovery Time	GBW SR	$G = 1$ $V_{IN} \bullet G = V_{S}$		* * *			35 0.01 60		kHz V/μs μs
OUTPUT Voltage Output Swing from Rail ⁽²⁾ $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	Vo	$R_L = 100k\Omega, \ A_{OL} \ge 70dB$ $R_L = 100k\Omega, \ A_{OL} \ge 100dB$ $R_L = 100k\Omega, \ A_{OL} \ge 100dB$ $R_L = 20k\Omega, \ A_{OL} \ge 100dB$		* *			50 75	250 250 300	mV mV mV
T _A = -40°C to +85°C Short-Circuit Current Single Versions Dual Versions Capacitive Load Drive	I _{SC}	$R_L = 20k\Omega$, $A_{OL} \ge 100dB$		* *		See	-21/+4 -50/+4 Typical C	300	mV mA mA
POWER SUPPLY Specified Voltage Range Operating Voltage Range Quiescent Current (per amplifier) T _A = -40°C to +85°C	V _S	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ $I_O = 0$ $I_O = 0$	*	*	*	±1.35	±15 ±27	±18 ±38 ±45	V V μA μA
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance 8-Pin DIP SO-8 Surface Mount	$ heta_{\sf JA}$		* * *	*	* *	-40 -55 -55	100 150	+85 +125 +125	°C/W °C/W
14-Pin DIP SO-14 Surface Mount				*			80 100		°C/W

^{*} Specifications the same as OPA251UA, PA.

NOTES: (1) The negative sign indicates input bias current flows out of the input terminals. (2) Output voltage swings are measured between the output and power supply rails.

ABSOLUTE MAXIMUM RATINGS(1)

Supply Voltage, V+ to V	36V
Input Voltage ⁽²⁾	(V–) –0.5V to (V+) +0.5V
Output Short Circuit to Ground(3)	Continuous
Operating Temperature	55°C to +125°C
Storage Temperature	55°C to +125°C
Junction Temperature	150°C
Lead Temperature (soldering, 10s)	300°C

NOTES: (1) Stresses above these ratings may cause permanent damage. (2) Input terminals are diode-clamped to the power supply rails. Input signals that can swing more that 0.5V beyond the supply rails should be current-limited to 5mA or less. (3) One amplifier per package.



This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

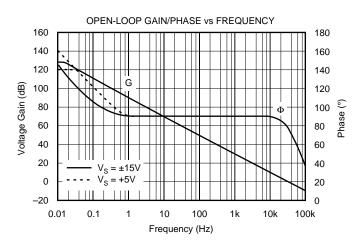
PRODUCT	SPECIFIED VOLTAGE	OPERATING VOLTAGE RANGE	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾	SPECIFICATION TEMPERATURE RANGE
OPA241 SERIES					
Single OPA241PA OPA241UA	2.7V to 5V 2.7V to 5V	2.7V to 36V 2.7V to 36V	8-Pin DIP SO-8 Surface Mount	006 182	−40°C to +85°C −40°C to +85°C
Dual OPA2241PA OPA2241UA	2.7V to 5V 2.7V to 5V	2.7V to 36V 2.7V to 36V	8-Pin DIP SO-8 Surface Mount	006 182	−40°C to +85°C −40°C to +85°C
Quad OPA4241PA OPA4241UA	2.7V to 5V 2.7V to 5V	2.7V to 36V 2.7V to 36V	14-Pin DIP SO-14 Surface Mount	010 235	−40°C to +85°C −40°C to +85°C
OPA251 SERIES					
Single OPA251PA OPA251UA	±15V ±15V	2.7V to 36V 2.7V to 36V	8-Pin DIP SO-8 Surface Mount	006 182	−40°C to +85°C −40°C to +85°C
Dual OPA2251PA OPA2251UA	±15V ±15V	2.7V to 36V 2.7V to 36V	8-Pin DIP SO-8 Surface Mount	006 182	−40°C to +85°C −40°C to +85°C
Quad OPA4251PA OPA4251UA	±15V ±15V	2.7V to 36V 2.7V to 36V	14-Pin DIP SO-14 Surface Mount	010 235	-40°C to +85°C -40°C to +85°C

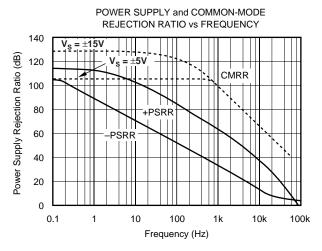
NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book.

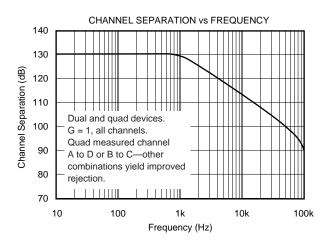
TYPICAL PERFORMANCE CURVES

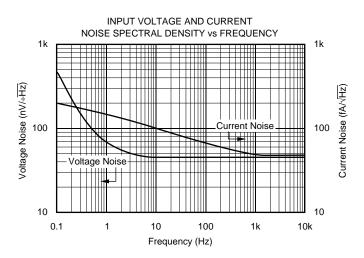
At T_A = +25°C, and R_L = 100k Ω connected to $V_S/2$ (ground for V_S = ±15V), unless otherwise noted.

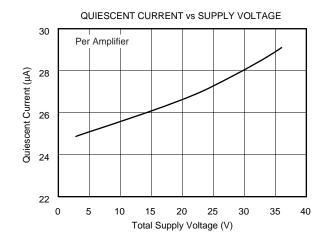
Curves apply to OPA241 and OPA251 unless specified.

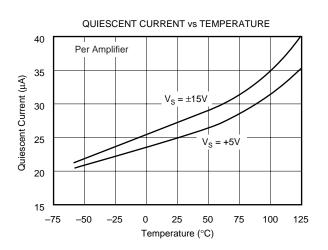








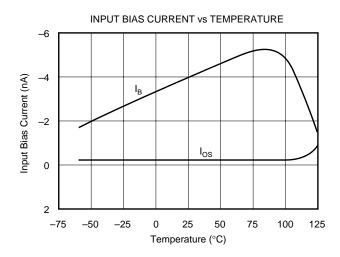


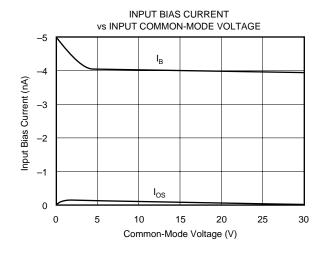


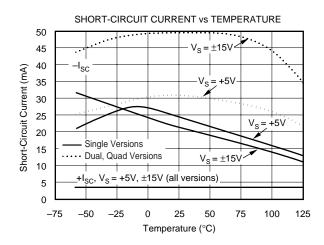
TYPICAL PERFORMANCE CURVES (CONT)

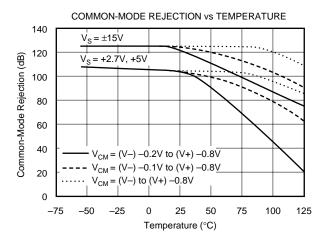
At T_A = +25°C, and R_L = 100k Ω connected to $V_S/2$ (ground for V_S = ±15V), unless otherwise noted.

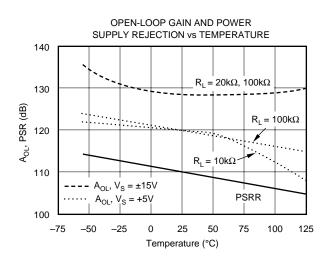
Curves apply to OPA241 and OPA251 unless specified.

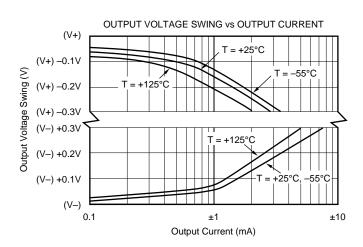






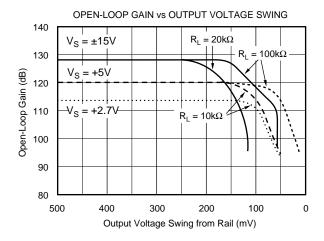


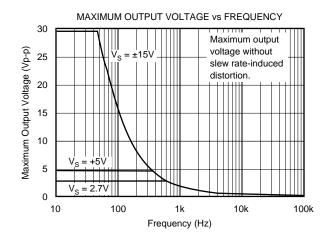


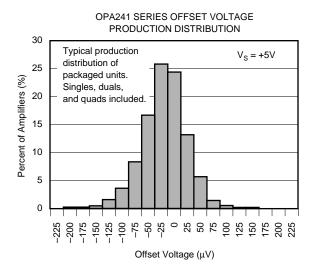


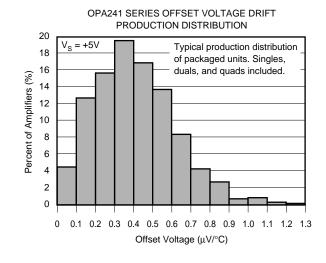
TYPICAL PERFORMANCE CURVES (CONT)

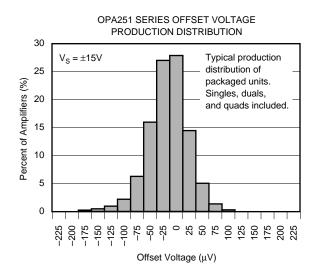
At T_A = +25°C, and R_L = 100k Ω connected to $V_S/2$ (ground for V_S = ±15V), unless otherwise noted. Curves apply to OPA241 and OPA251 unless specified.

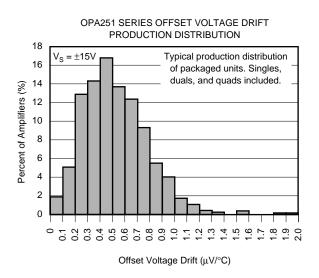








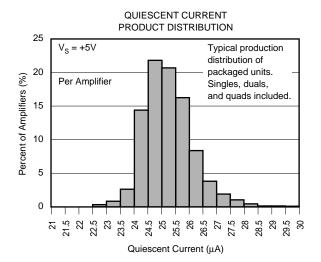


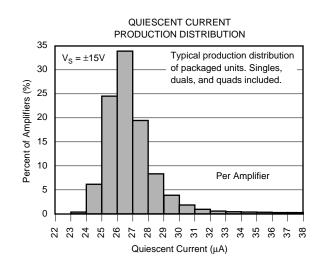


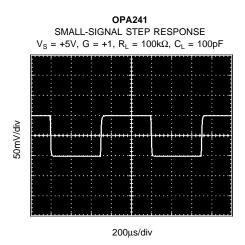
TYPICAL PERFORMANCE CURVES (CONT)

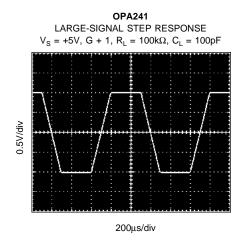
At T_A = +25°C, and R_L = 100k Ω connected to $V_S/2$ (ground for V_S ±15V), unless otherwise noted.

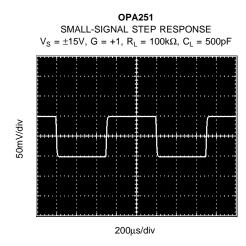
Curves apply to OPA241 and OPA251 unless specified.

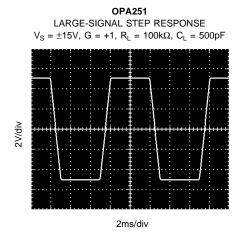












APPLICATIONS INFORMATION

The OPA241 and OPA251 series are unity-gain stable and suitable for a wide range of general purpose applications. Power supply pins should be bypassed with 0.01µF ceramic capacitors.

OPERATING VOLTAGE

The OPA241 series is laser-trimmed for low offset voltage and drift at low supply voltage ($V_S = +5V$). The OPA251 series is trimmed for $\pm 15V$ operation. Both products operate over the full voltage range (+2.7V to +36V or $\pm 1.35V$ to $\pm 18V$) with some compromises in offset voltage and drift performance. However, all other parameters have similar performance. Key parameters are guaranteed over the specified temperature range, $-40^{\circ}C$ to $+85^{\circ}C$. Most behavior remains unchanged throughout the full operating voltage range. Parameters which vary significantly with operating voltage or temperature are shown in typical performance curves.

OFFSET VOLTAGE TRIM

As mentioned previously, offset voltage of the OPA241 series is laser-trimmed at ± 5 V. The OPA251 series is trimmed at ± 15 V. Because the initial offset is so low, user adjustment is usually not required. However, the OPA241 and OPA251 (single op amp versions) provide offset voltage trim connections on pins 1 and 5. Offset voltage can be adjusted by connecting a potentiometer as shown in Figure 1. This adjustment should be used only to null the offset of the op amp, not to adjust system offset or offset produced by the signal source. Nulling offset could degrade the offset drift behavior of the op amp. While it is not possible to predict the exact change in drift, the effect is usually small.

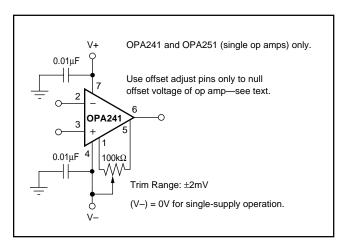


FIGURE 1. OPA241 and OPA251 Offset Voltage Trim Circuit.

CAPACITIVE LOAD AND STABILITY

The OPA241 series and OPA251 series can drive a wide range of capacitive loads. However, all op amps under certain conditions may be unstable. Op amp configuration, gain, and load value are just a few of the factors to consider when determining stability.

Figures 2 and 3 show the regions where the OPA241 series and OPA251 series have the potential for instability. As shown, the unity gain configuration with low supplies is the most susceptible to the effects of capacitive load. With $V_{\rm S}=+5V,\ G=+1,$ and $I_{\rm OUT}=0,$ operation remains stable with load capacitance up to approximately 200pF. Increasing supply voltage, output current, and/or gain significantly improves capacitive load drive. For example, increasing the supplies to $\pm15V$ and gain to 10 allows approximately 2700pF to be driven.

One method of improving capacitive load drive in the unity gain configuration is to insert a resistor inside the feedback loop as shown in Figure 4. This reduces ringing with large capacitive loads while maintaining dc accuracy. For example, with $V_S=\pm 1.35 V$ and $R_S=5 k\Omega$, the OPA241 series and OPA251 series perform well with capacitive loads in excess of 1000pF. Without the series resistor, capacitive load drive is typically 200pF for these conditions. However, this method will result in a slight reduction of output voltage swing.

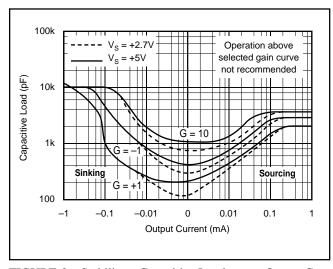


FIGURE 2. Stability—Capacitive Load versus Output Current for Low Supply Voltage.

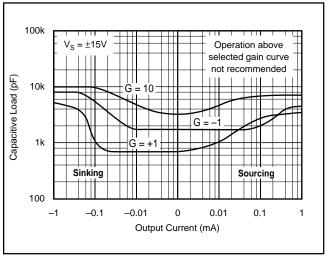


FIGURE 3. Stability—Capacitive Load versus Output Current for ±15V Supplies.



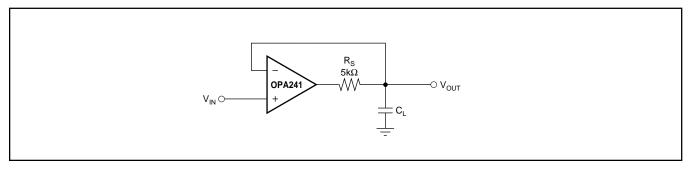


FIGURE 4. Series Resistor in Unity Gain Configuration Improves Capacitive Load Drive.

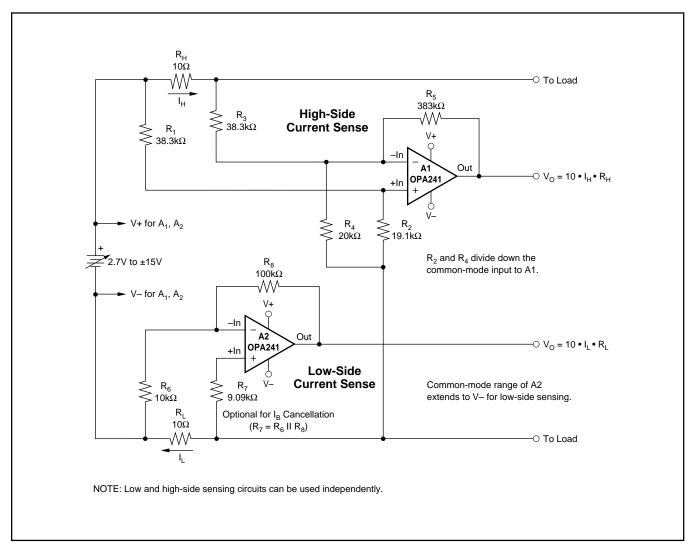


FIGURE 5. Low and High-Side Battery Current Sensing.



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
OPA2241PA	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2241PAG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2241UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2241UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2241UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2241UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2251PA	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2251PAG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2251UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2251UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2251UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2251UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA241PA	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA241PAG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA241UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA241UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA241UA/2K5E4	PREVIEW	SOIC	D	8		TBD	Call TI	Call TI
OPA241UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA241UAE4	PREVIEW	SOIC	D	8		TBD	Call TI	Call TI
OPA241UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA251PA	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA251PAG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA251UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA251UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA251UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA251UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS &	CU NIPDAU	Level-3-260C-168 HR

PACKAGE OPTION ADDENDUM

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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
OPA4241PA	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA4241PAG4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA4241UA	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA4241UA/2K5	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA4241UA/2K5G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA4241UAG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA4251PA	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA4251PAG4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA4251UA	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA4251UA/2K5	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA4251UA/2K5G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA4251UAG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

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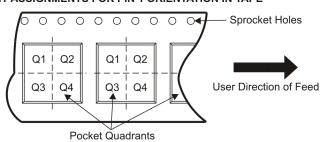
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2241UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2251UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA241UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA251UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4241UA/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
OPA4251UA/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2241UA/2K5	SOIC	D	8	2500	346.0	346.0	29.0
OPA2251UA/2K5	SOIC	D	8	2500	346.0	346.0	29.0
OPA241UA/2K5	SOIC	D	8	2500	346.0	346.0	29.0
OPA251UA/2K5	SOIC	D	8	2500	346.0	346.0	29.0
OPA4241UA/2K5	SOIC	D	14	2500	346.0	346.0	33.0
OPA4251UA/2K5	SOIC	D	14	2500	346.0	346.0	33.0

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



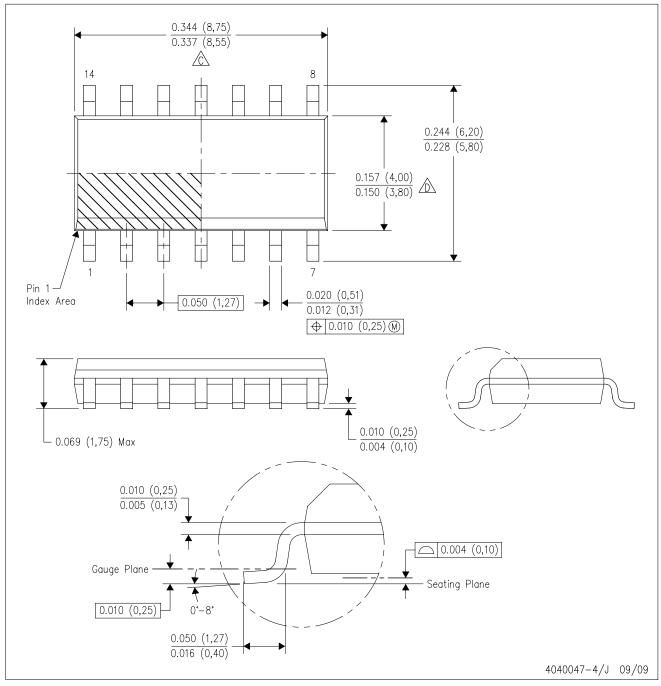
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



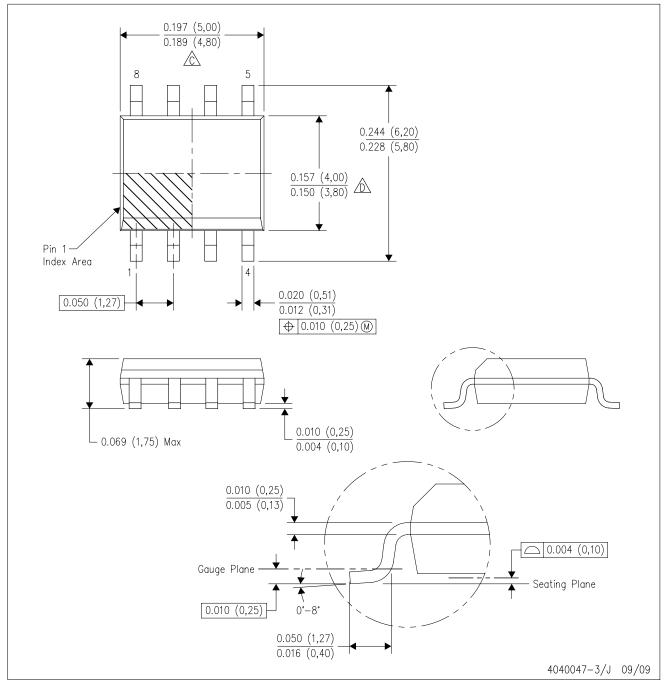
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



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